

To: All Chairs of Department and Heads of Graduate Studies of the Engineering Schools

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Subject: Notification of call for applications for International Exchange Program of the Engineering Schools

Call for Applications

International Exchange Program (Outbound) of the Engineering Schools

***Revised and updated**

We are pleased to announce a call for applications for the **International Exchange Program (Outbound) of the Engineering Schools**. Students who wish to apply for this exchange program must submit the below documents to the International Cooperation Office of the Engineering Schools.

Before applying, students must read through the following website and comply with the guidelines below.

<http://www.eng.titech.ac.jp/english/international/iep.html>

- ◆ **Program Categories Open for Application: C1~C4**
- ◆ **Period of start studying abroad: Between May 2017 and August 2017**
- ◆ **Prospective Applicants: Students who will be enrolled in a master's or doctoral degree program at the Engineering Schools as of April 1, 2017**
 - The former Graduate School of Engineering has been replaced by the Engineering Schools, which consist of three schools: School of Engineering, School of Materials and Chemical Technology, and School of Environment and Society. Students of the former Graduate School of Engineering are also eligible to apply. However, those who study at the Departments of Social and Human Sciences, Innovation Science, and Technology and Innovation Management (professional master's degree program) in the School of Environment and Society are not eligible. Students in the second year of their master's degree program and doctoral degree students belong to the school to which their academic supervisor is affiliated.
- ◆ **Deadline: 17:00 on Wednesday, January 11, 2017**
 - Applications that arrive after this deadline will not be processed, regardless of reason.
- ◆ **Interview: From 13:10 on Wednesday, January 18, 2017**
 - Details regarding location and time for the interview will be notified by email after the submission of the application documents.
 - If an applicant will not be able to attend the interview for legitimate reasons, the **Statement of Reason** must be submitted with the other application documents to request the interview to be scheduled for a different time. The applicant may not request to reschedule the interview after the submission of the application.
- ◆ **Application Documents**
 1. **Application form** (Please use the latest version.)
 2. Resume in English (Free format. Click **here** for sample resume.)
 3. A copy of your English language test scores (TOEFL® or TOEIC® score report)
 - a. Some universities may have their own English language requirements, such as TOEFL iBT® or IELTS scores. The applicant must check with the university in which he/she wishes to enroll.
 - b. Applicants may submit a new, better score report to the interviewers in person during the interview.
 4. Academic Transcript (Both in Japanese and English)

The transcript must include your academic record of the previous year. Students in their first year of a master's degree program must also attach their undergraduate academic transcripts.

 - Incomplete applications and applications received after the deadline will not be accepted.
 - Submitted documents will not be returned.
 5. Statement of Reason (Free format)
 - C3-b applicants who cannot apply for or was rejected by the **university-wide program conducted by International Student Exchange Division** (See the link)
 - All C4 applicants (Both by applicants and by their Chair of Department, Head of Graduate Studies or academic advisor)

◆ **How to Submit Your Application Documents**

- Hard copies of documents 1, 2, 3, and 4 above must be submitted by campus mail or by hand to the International Cooperation Office of the Engineering Schools. The documents must be single-sided A4 copies. Clip all sheets together.
- Documents 1 and 2 must also be sent by email.

◆ **Where to Submit or Inquire**

International Cooperation Office of the Engineering Schools
 (Main Bldg., Rm 50, 2 Fl)
 Mailbox: H106
 Extension: 3969
 Email: ko.intfl@jim.titech.ac.jp

◆ **Application Guidelines**

Program Outline	<p>The Engineering Schools offer an international exchange program that consists of five categories, C1, C2, C3, C4, and C5. Study abroad expenses are partially provided to successfully nominated students.</p> <p>Based on the Engineering Schools' funding policy for its international exchange program, financial support is provided for</p> <ol style="list-style-type: none"> 1) Outbound students who will participate in research under the supervision of professors in the host university 2) Outbound students who will conduct research to broaden their own research field <p>Students engaging in the following are NOT eligible to receive funding through this program.</p> <ol style="list-style-type: none"> 1) Joint research between an overseas university and Tokyo Tech 2) Research related to students' thesis research or doctoral dissertation 3) Study abroad solely focusing on acquiring course credits
Call for Applications	<p>Announcements will be made on the former Graduate School of Engineering's website and also will be sent to each chair of department.</p> <p>Applications for C1 will be processed only in January. Applications for C5 will be processed as needed.</p>
Eligibility	<ol style="list-style-type: none"> 1) Students on leave of absence are NOT eligible. 2) Applicants planning to study in their home country are NOT eligible. 3) Consideration will be given to students who actively participate in international activities or classes held by the Engineering Schools or Tokyo Tech. Please mention this in the application form if you have such experience. 4) Only students with a GPA of 2.3 or higher are eligible to apply for C1 and C2.
Language Proficiency Requirements	<p>Applicants must satisfy the following English proficiency requirements: TOEFL iBT[®] score of 70 or higher and/or TOEIC score of 650 or higher. However, even if their score is below this level, students may apply for the program if they have special reasons (e.g., have proficiency in language used in the country where the host university is located, have good English conversation ability that is not reflected in the scores). In such cases, students must attach a statement (free format) explaining these skills to their application.</p>
Screening Method	<p>Face to face interview in English</p> <ul style="list-style-type: none"> • An applicant will be interviewed by multiple faculty members for 10 minutes (The first 5 minutes is for self-introduction, motivation, and research plan presentation, the latter 5 minutes is for questions and answers) • An applicant is allowed to distribute A4-size handouts • An applicant is not allowed to read scripts or use a PC and/or projector <p>Note: If the number of applicants is large, only those selected by the initial screening (examination of application documents) will be interviewed.</p>

Financial Support for Outbound Students	<ul style="list-style-type: none"> • Round trip travel expense and/or scholarship is provided. • Application fees and expenses for VISA acquisition are NOT provided. • In the case of Japanese government (MEXT) scholarship students, only the round trip travel expense (airfare) at cost is provided. Also please note that there might be a possibility for those who participate in this program to lose their eligibility to receive the MEXT scholarship not only during the stay abroad but also after coming back to Tokyo Tech. Please confirm the detailed and latest information about this with Student Support Division (gak.sei@jim.titech.ac.jp). • If other scholarships or financial support are provided to students by Tokyo Tech, the amount of the financial support under this program will be adjusted
Important Points to Note	<ul style="list-style-type: none"> • Applicants must carefully determine their period of study abroad, taking into consideration the academic calendars of Tokyo Tech and the university in which they wish to enroll. The International Cooperation Office of the Engineering Schools will NOT coordinate schedules of students with classes or courses at Tokyo Tech. It is the applicant's responsibility to manage his/her own schedule. • Applicants for C2 should note that some universities require applications to be completed approximately 3 months prior to enrollment.

◆ **Grade Requirements**

Students applying for categories C1, C2, C3, and C4 must state their GPA for the previous academic year in their application form. GPA must be calculated based on the calculation method below. To apply for categories C1 and C2, students must have a GPA of 2.3 or higher.

How to calculate your Grade Point Average (GPA)

Grade Conversion Table						
	Grade					
Four-level grading scale (Type 1)	—	Excellent	Good	Fair	Fail	
Four-level grading scale (Type 2)	—	A	B	C	F	
Four-level grading scale (Type 3)	—	100–80	79–70	69–60	59 or lower	
Five-level grading scale (Type 4)	100–90	89–80	79–70	69–60	59 or lower	
Five-level grading scale (Type 5)	S	A	B	C	F	
Five-level grading scale (Type 6)	A	B	C	D	F	
Grade Evaluation Point (GEP)	3	3	2	1	0	

$$\frac{(\text{Number of Credit for GEP3} \times 3) + (\text{Number of Credit for GEP2} \times 2) + (\text{Number of Credit for GEP1} \times 1) + (\text{Number of Credit for GEP0} \times 0)}{\text{Total Number of Credits}}$$

First, refer to the above table to convert your grades to Grade Evaluation Points (GEP) and calculate the following.

- I The number of credits with a GEP of 3 multiplied by three
- II The number of credits with a GEP of 2 multiplied by two
- III The number of credits with a GEP of 1 multiplied by one
- IV The number of credits with a GEP of 0 multiplied by zero

To calculate your GPA, divide the sum of I, II, III, and IV by the number of total credits earned.

◆ **Supplements**

The SERP partner universities have their own requirements for the C1 category. [See the link.](#)

* New requirements might be added. Please check out the latest information when you submit the applications.